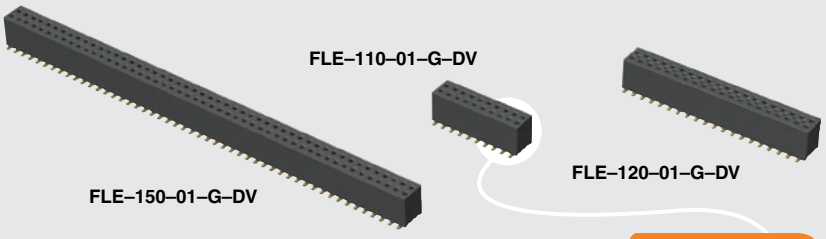


(1.27 mm) .050"

FLE SERIES

COST-EFFECTIVE RELIABLE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?FLE

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au over 50 µ" (1.27 µm) Ni
Current Rating:
2.9 A per pin (2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.83 mm) .072" to (4.37 mm) .172" or pass-through
Normal Force:
100 grams (0.98 N)
Max Cycles:
100+
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

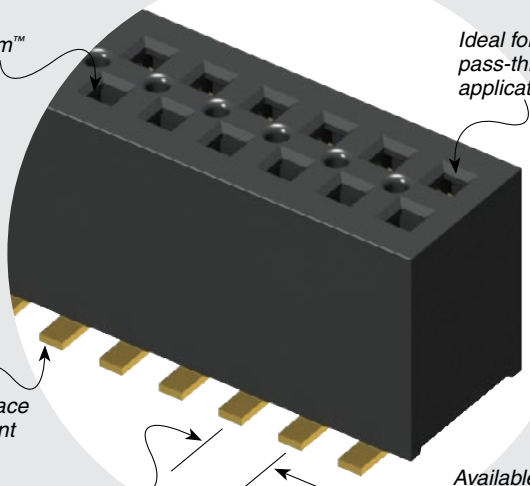
ALSO AVAILABLE (MOQ Required)

- Other platings

Board Mates:
FTSH, FTS, FW
Cable Mates:
FFMD*, FMTP

***Note:** Standard FFMD callout will not mate with FLE, SFMC. Must use gold plated callouts. (See drawing on web.)

TIGER™ BEAM CONTACT



HIGH-SPEED CHANNEL PERFORMANCE

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

8 Gbps

FLE	–	1	NO. PINS PER ROW	–	01	PLATING OPTION	–	DV	–	OPTIONS

02 thru 50

–G
= 10 µ" (0.25 µm) Gold

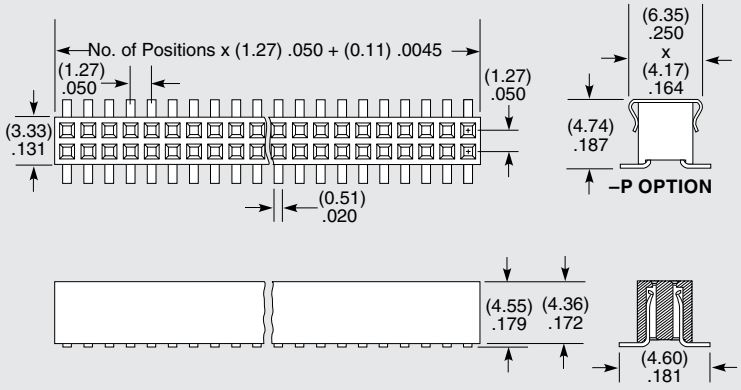
–A
= Alignment Pin (Metal or plastic at Samtec discretion) (3 positions minimum)

–K
= (4.25 mm) .167" DIA Polyimide film Pick & Place Pad (5 positions minimum)

–P
= Metal Pick & Place Pad (5 positions minimum)

–TR
= Tape & Reel

–FR
= Full Reel Tape & Reel Packaging (Must order maximum quantities per reel. Contact Samtec for parts per reel)



Note:
Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.